

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Fu-Wei YAO	10/05/2011
Chun-Wei HSU	10/06/2011
Chen-Ju YU	10/05/2011
Jiun-Lei Jerry YU	10/05/2011
Fu-Chih YANG	10/05/2011
Chih-Wen HSIUNG	10/05/2011
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13270502
CORRESPONDENCE DATA	
Fax Number:	(703)518-5499
Phone:	7036841111
Email:	tsmc@ipfirm.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	Lowe Hauptman Ham & Berner, LLP
Address Line 1:	1700 Diagonal Road
Address Line 2:	Suite 300
Address Line 4:	Alexandria, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	T5057-R566

OP \$40.00 13270502

501718382

PATENT
 REEL: 027199 FRAME: 0777

NAME OF SUBMITTER:

Randy A. Noranbrock

Total Attachments: 2

source=efiledassgn#page1.tif

source=efiledassgn#page2.tif

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|-----------------|----------------------|
| 1) Fu-Wei YAO | 4) Jiun-Lei Jerry YU |
| 2) Chun-Wei HSU | 5) Fu-Chih YANG |
| 3) Chen-Ju YU | 6) Chih-Wen HSIUNG |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR STRUCTURE AND METHOD OF FORMING THE SAME

(a) for which an application for United States Letters Patent was filed on 10-11-2011, and identified by United States Patent Application No. 13/270,502; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) ✓ Fu wei Yao
Name: Fu-Wei YAO


✓ 10.08.2011
Date:

2) ✓ Chun Wei Hsu
Name: Chun-Wei HSU


✓ 10.06.2011
Date:

3) ✓ Chen-Ju Yu
Name: Chen-Ju YU

✓ 10.05.2011
Date:

4) ✓ 
Name: Jiun-Lei Jerry YU

✓ 10.05.2011
Date:

5) ✓ 
Name: Fu-Chih YANG

✓ 10.05.2011
Date:

6) ✓ 
Name: Chih-Wen HSIUNG

✓ 10.05.2011
Date: